# Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: http://www.renesas.com

April 1<sup>st</sup>, 2010 Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

Not read

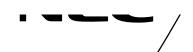
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# MOS FIELD EFFECT TRANSISTOR 2SK4202

# **SWITCHING N-CHANNEL POWER MOS FET**

### **DESCRIPTION**

The 2SK4202 is N-channel MOS Field Effect Transistor designed for high current switching applications.

### **FEATURES**

• Low on-state resistance

 $R_{DS(on)} = 7.5 \text{ m}\Omega \text{ MAX}. \text{ (V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 42 \text{ A})$ 

Low input capacitance

Ciss = 6300 pF TYP. (VDS = 10 V)

### ORDERING INFORMATION

PART NUMBER	LEAD PLATING	PACKING	PACKAGE
2SK4202-S19-AY Note	Pure Sn (Tin)	Tube 50 p/tube	TO-220 typ. 1.9 g

Note Pb-free (This product does not contain Pb in the external electrode).

# ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (Ves = 0 V)	VDSS	60	V
Gate to Source Voltage (V <sub>DS</sub> = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	ID(DC)	±84	Α
Drain Current (pulse) Note1	D(pulse)	±240	Α
Total Power Dissipation (Tc = 25°C)	P <sub>T1</sub>	104	W
Total Power Dissipation (T <sub>A</sub> = 25°C)	Рт2	1.5	W
Channel Temperature	Tch	150	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°С
Single Avalanche Current Note2	las	37	Α
Single Avalanche Energy Note2	Eas	137	mJ

**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

**2.** Starting T<sub>ch</sub> = 25°C, V<sub>DD</sub> = 30 V, R<sub>G</sub> = 25  $\Omega$ , V<sub>GS</sub> = 20  $\rightarrow$  0 V, L = 100  $\mu$ H

## THERMAL RESISTANCE

Channel to Case Thermal Resistance  $R_{th(ch-C)}$ 1.20 °C/W Channel to Ambient Thermal Resistance 83.3 °C/W Rth(ch-A)

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**ELECTRICAL CHARACTERISTICS (TA = 25°C)** 

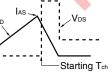
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V			10	μΑ
Gate Leakage Current	Igss	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V			±100	nA
Gate to Source Cut-off Voltage	V <sub>GS(off)</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	3.0	4.0	V
Forward Transfer Admittance Note	yfs	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 30 A	16	34		S
Drain to Source On-state Resistance Note	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 42 A		5.7	7.5	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = 10 V,		6300		pF
Output Capacitance	Coss	V <sub>GS</sub> = 0 V,		650		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		380		pF
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 30 V, I <sub>D</sub> = 42 A,		30		ns
Rise Time	tr	V <sub>GS</sub> = 10 V,		18		ns
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 0 \Omega$		68		ns
Fall Time	tf			9		ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DD</sub> = 48 V,	5	106		nC
Gate to Source Charge	Qgs	V <sub>GS</sub> = 10 V,		29		nC
Gate to Drain Charge	Q <sub>GD</sub>	I <sub>D</sub> = 84 A	5)	35		nC
Body Diode Forward Voltage Note	V <sub>F(S-D)</sub>	I <sub>F</sub> = 84 A, V <sub>GS</sub> = 0 V		1.0	1.5	V
Reverse Recovery Time	trr	IF = 84 A, VGS = 0 V,		47		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		76		nC

Note Pulsed

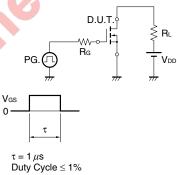
## TEST CIRCUIT 1 AVALANCHE CAPABILITY

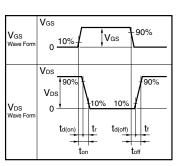
# $V_{GS} = 20 \rightarrow 0 \text{ V}$ $V_{GS} = 20 \rightarrow 0 \text{ V}$

### -



# **TEST CIRCUIT 2 SWITCHING TIME**

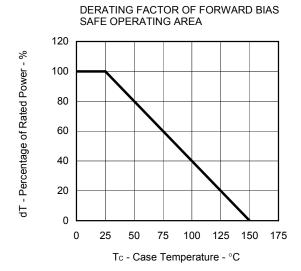


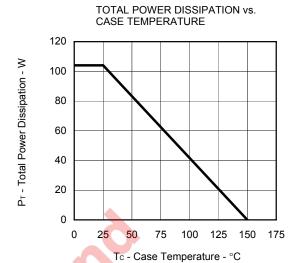


# **TEST CIRCUIT 3 GATE CHARGE**

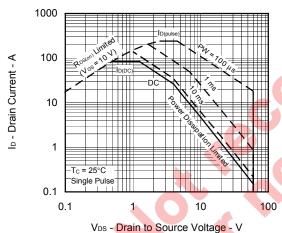
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# TYPICAL CHARACTERISTICS (TA = 25°C)

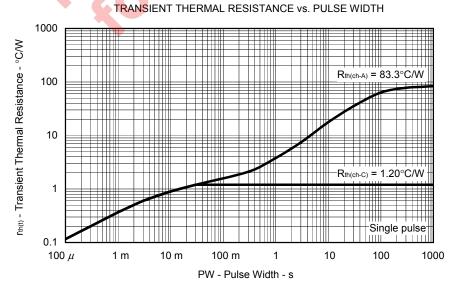






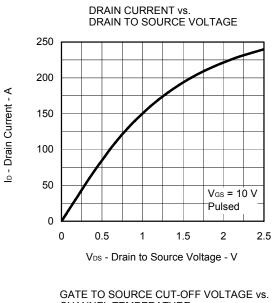


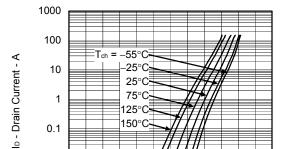




3







2

0.01

0.001

0

FORWARD TRANSFER CHARACTERISTICS

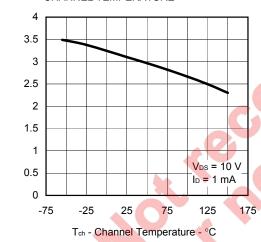
3 V<sub>GS</sub> - Gate to Source Voltage - V

Pulsed

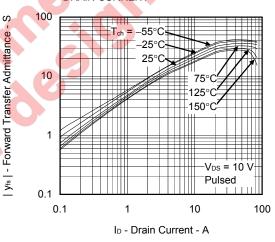
5

6

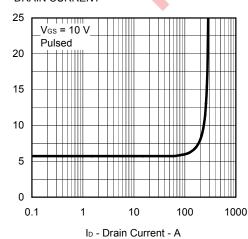
CHANNEL TEMPERATURE



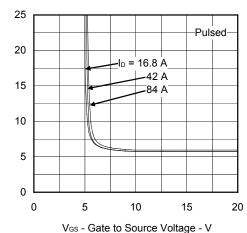
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

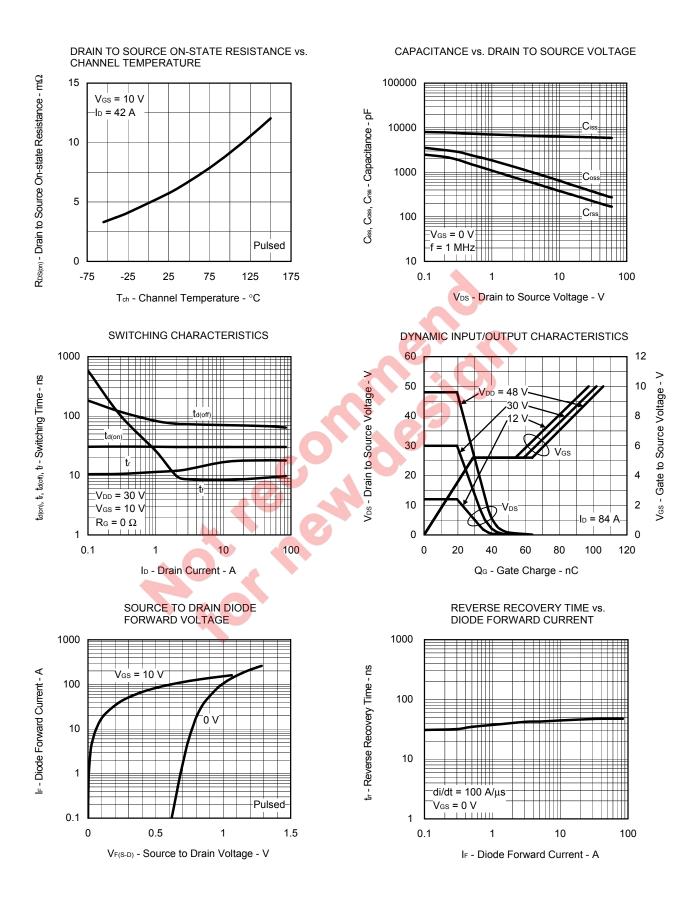


 $\mathsf{Res}_{\text{(on)}}$  - Drain to Source On-state Resistance -  $m\Omega$ 

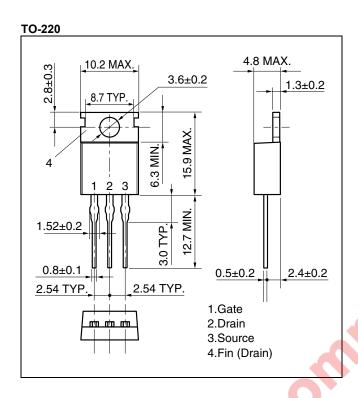
VGS(off) - Gate to Source Cut-off Voltage - V

R<sub>DS(on)</sub> - Drain to Source On-state Resistance - mΩ

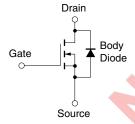




# <R> PACKAGE DRAWING (Unit: mm)



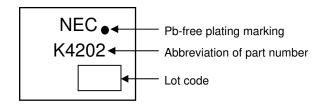
# **EQUIVALENT CIRCUIT**



**Remark** Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.



## MARKING INFORMATION



### RECOMMENDED SOLDERING CONDITIONS

The 2SK4202 should be soldered and mounted under the following recommended conditions.

For soldering methods and conditions other than those recommended below, please contact an NEC Electronics sales representative.

For technical information, see the following website.

Semiconductor Device Mount Manual (http://www.necel.com/pkg/en/mount/index.html)

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Wave soldering	Maximum temperature (Solder temperature): 260°C or below Time: 10 seconds or less Maximum chlorine content of rosin flux: 0.2% (wt.) or less	THDWS
Partial heating	Maximum temperature (Pin temperature): 350°C or below Time (per side of the device): 3 seconds or less Maximum chlorine content of rosin flux: 0.2% (wt.) or less	P350

Caution Do not use different soldering methods together (except for partial heating).

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